

RELIABILITY REPORT
FOR
MAX824
PLASTIC ENCAPSULATED DEVICES

August 14, 2013

MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

Approved by
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Conclusion

The MAX824 successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX823/MAX824/MAX825 microprocessor (μ P) supervisory circuits combine reset output, watchdog, and manual reset input functions in 5-pin SOT23 and SC70 packages. They significantly improve system reliability and accuracy compared to separate ICs or discrete components. The MAX823/MAX824/MAX825 are specifically designed to ignore fast transients on VCC. Seven preprogrammed reset threshold voltages are available (see *Reset Threshold Table* in the full data sheet). All three devices have an active-low reset output, which is guaranteed to be in the correct state for VCC down to 1V. The MAX823 also offers a watchdog input and manual reset input. The MAX824 offers a watchdog input and a complementary active-high reset. The MAX825 offers a manual reset input and a complementary active-high reset. The Selector Guide explains the functions offered in this series of parts.

II. Manufacturing Information

A. Description/Function:	5-Pin Microprocessor Supervisory Circuits with Watchdog Timer and Manual Reset	
B. Process:	B12	
C. Fabrication Location:	USA	
D. Assembly Location:	Malaysia, Thailand	Thailand, Malaysia
E. Date of Initial Production:	Pre 1997	

III. Packaging Information

A. Package Type:	5-pin SOT23	5-pin SC70
B. Lead Frame:	Copper	Copper
C. Lead Finish:	100% matte Tin	100% matte Tin
D. Die Attach:	Conductive	Conductive
E. Bondwire:	Au (1 mil dia.)	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	#05-1601-0010	#05-1601-0111
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1	Level 1
J. Single Layer Theta Ja:	324.3°C/W	324°C/W
K. Single Layer Theta Jc:	82°C/W	115°C/W
L. Multi Layer Theta Ja:	255.9°C/W	324°C/W
M. Multi Layer Theta Jc:	81°C/W	115°C/W

IV. Die Information

A. Dimensions:	42 X 36 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Minimum Metal Width:	1.2 microns (as drawn)
E. Minimum Metal Spacing:	1.2 microns (as drawn)
F. Isolation Dielectric:	SiO ₂
G. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% for all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{6.21}{192 \times 4340 \times 317 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 11.8 \times 10^{-9}$$

$$\lambda = 11.8 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the B12 Process results in a FIT Rate of 0.02 @ 25C and 0.33 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (ESD lot I2PLBQ002A D/C 0037, Latch-Up lot STWIIQ003A)

The MS05-8 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX824

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C	DC Parameters	77	2	I16BBQ001D, D/C 0135
	Biased	& functionality	80	0	IITWBHY001B, D/C 9943
	Time = 192 hrs.		80	0	NTWCGB010F, D/C 9747
			80	0	BTWHBS006F, D/C 9645

Note 1: Life Test Data may represent plastic DIP qualification lots.